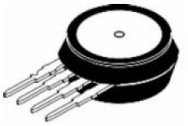
MPX2200A, MPX2200D, MPX2200DP
MPX2200AP, MPX2200GP

Datasheet

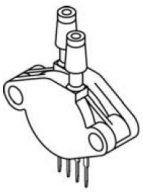
200 kPa on-chip temperature compensated silicon pressure sensors

UNIBODY PACKAGES



CASE 344-15

CASE 344B-01



CASE 344C-01

Features

- Temperature Compensated Over 0°C to +85°C
- ±0.25% Linearity (MPX2200D)
- Easy-to-Use Chip Carrier Package Options
- Absolute, Differential, and Gauge Options

Applications

- Pump/Motor Control
- Robotics
- Level Detectors
- Medical Diagnostics
- Pressure Switching
- Barometers
- Altimeters

Description

The MPX2200 series devices are silicon piezoresistive pressure sensor providing a highly accurate and linear voltage output directly proportional to the applied pressure. The sensor is a single monolithic silicon diaphragm with the strain gauge and a thin-film resistor network integrated on-chip. The chip is laser trimmed for precise span and offset calibration and temperature compensation. They are designed for use in applications such as pump/ motor controllers, robotics, level indicators, medical diagnostics, pressure switching, barometers, altimeters, etc.

1 ORDERING INFORMATION

ORDERING INFORMATION									
Device Name	Package Options	Case No.	# of Ports				Pressure Type		Device Marking
			None	Single	Dual	Gauge	Differential	Absolute	
Unibody Package (MPX2200 Series)									
MPX2200A	Tray	344	•					•	MPX2200A
MPX2200D	Tray	344	•				•		MPX2200D
MPX2200DP	Tray	344C			•		•		MPX2200DP
MPX2200AP	Tray	344B		•				•	MPX2200AP
MPX2200GP	Tray	344B		•		•			MPX2200GP

2 Operating Characteristics

Table 1. Operating Characteristics (VS = 10 VDC, TA = 25°C unless otherwise noted, P1 > P2)

Characteristic	Symbol	Min	Typ	Max	Units
Differential Pressure Range(1)	P_{OP}	0	—	200	kPa
Supply Voltage(2)	V_S	—	10	16	V_{DC}
Supply Current	I_O	—	6.0	—	mAdc
Full Scale Span(3)	V_{FSS}	38.5	40	41.5	mV
Offset(4)	V_{OFF}	-1.0	—	1.0	mV
Sensitivity	ΔV/ΔP	—	0.2	—	mV/kPa
Linearity MPX2200D Series MPX2200A Series	—	-0.25 -1.0	— —	0.25 1.0	$\%V_{FSS}$
Pressure Hysteresis(0 to 200 kPa)	—	—	±0.1	—	$\%V_{FSS}$
Temperature Hysteresis(- 40°C to +125°C)	—	—	±0.5	—	$\%V_{FSS}$
Temperature Coefficient of Full Scale Span	TCV_{FSS}	-1.0	—	1.0	$\%V_{FSS}$
Temperature Coefficient of Offset	TCV_{OFF}	-1.0	—	1.0	mV
Input Impedance	Z_{IN}	1300	—	2500	Ω
Output Impedance	Z_{OUT}	1400	—	3000	Ω
Response Time(5) (10% to 90%)	t_R	—	1.0	—	ms
Warm-Up Time(6)	—	—	20	—	ms
Offset Stability(7)	—	—	±0.5	—	$\%V_{FSS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.
2. Device is ratiometric within this specified excitation range. Operating the device above the specified excitation range may induce additional error due to device self-heating.
3. Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
4. Offset (V_{OFF}) is defined as the output voltage at the minimum rated pressure.
5. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
6. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the pressure is stabilized.
7. Offset stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

3 Maximum Ratings

Table 1. Maximum ratings(1)

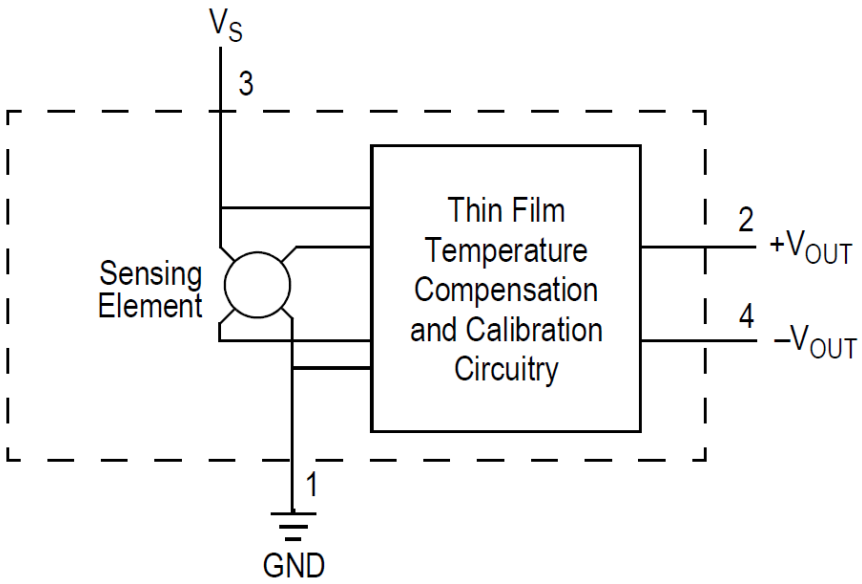
Rating	Max Value	Unit
Maximum Pressure (P1 > P2)	800	kPa
Storage Temperature	–40 to +125	°C
Operating Temperature	–40 to +125	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

4 Voltage Output versus Applied Differential

The output voltage of the differential or gauge sensor increases with increasing pressure applied to the pressure side (P1) relative to the vacuum side (P2). Similarly, output voltage increases as increasing vacuum is applied to the vacuum side (P2) relative to the pressure side (P1).Figure 1 shows a block diagram of the internal circuitry on the stand-alone pressure sensor chip

Figure 1. Temperature Compensated and Calibrated Pressure Sensor Schematic



5 On-Chip Temperature Compensation and Calibration

Figure 2. Output vs. Pressure Differential

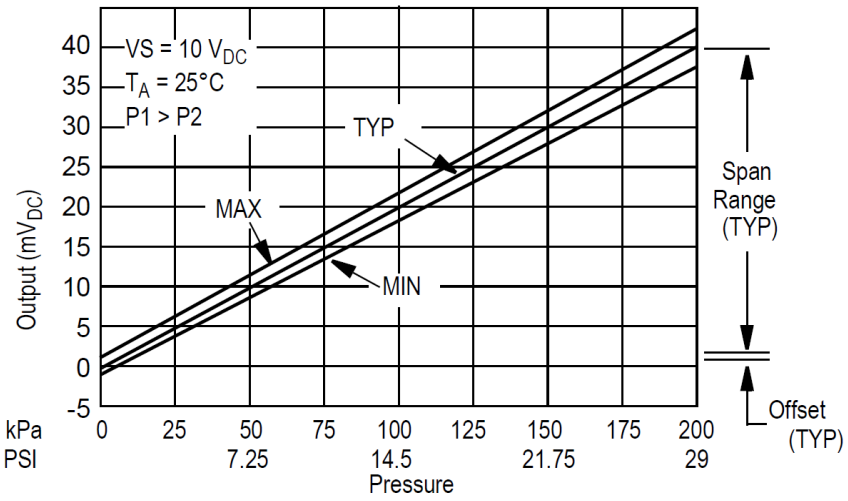


Figure 2 shows the output characteristics of the MPX2200 series at 25°C. The output is directly proportional to the differential pressure and is essentially a straight line. The effects of temperature on full scale span and offset are very small and are shown under Operating Characteristics.

Figure 3. Cross Sectional Diagram (not to scale)

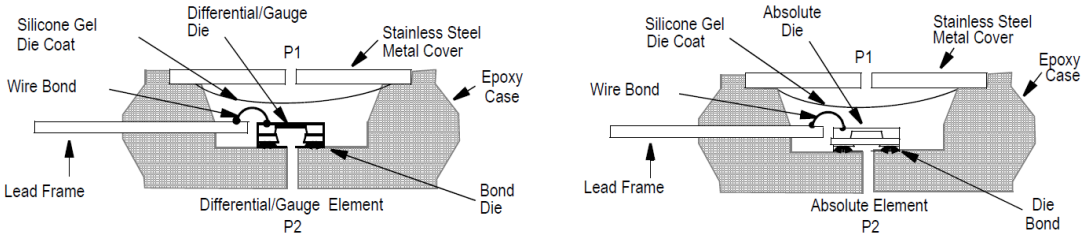
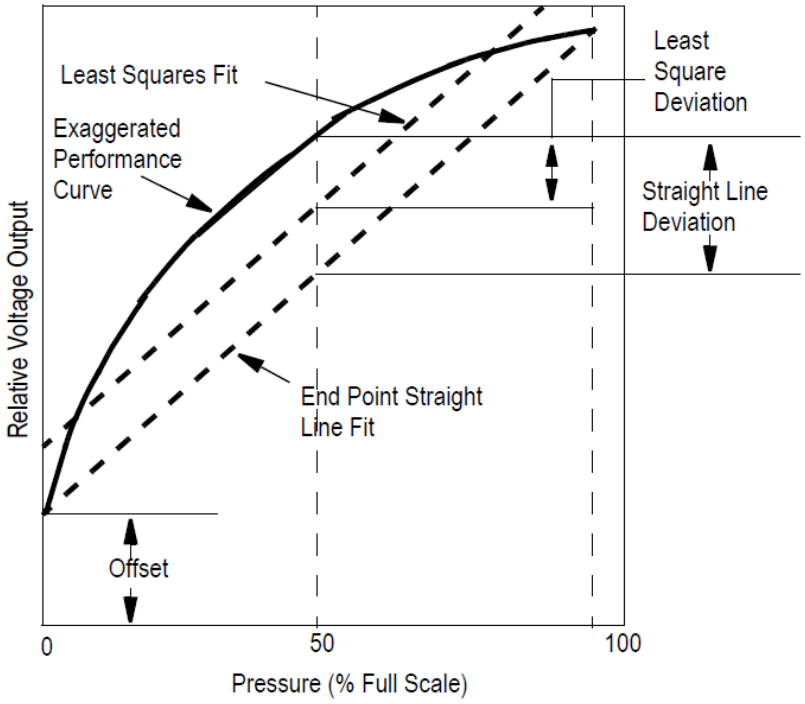


Figure 3 illustrates the differential/gauge die in the basic chip carrier (Case 344). A silicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the silicon diaphragm. The MPX2200 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media other than dry air may have adverse effects on sensor performance and long term reliability. Contact the factory for information regarding media compatibility in your application.

6 LINEARITY

Linearity refers to how well a transducer's output follows the equation: $V_{OUT} = V_{OFF}$ + sensitivity x P over the operating pressure range. There are two basic methods for calculating nonlinearity: (1) end point straight line fit (see Figure 4) or (2) a least squares best line fit. While a least squares fit gives the “best case” linearity error (lower numerical value), the calculations required are burdensome. Conversely, an end point fit will give the “worst case” error (often more desirable in error budget calculations) and the calculations are more straightforward for the user. ST specified pressure sensor linearities are based on the end point straight line method measured at the midrange pressure.

Figure 4. Linearity Specification Comparison



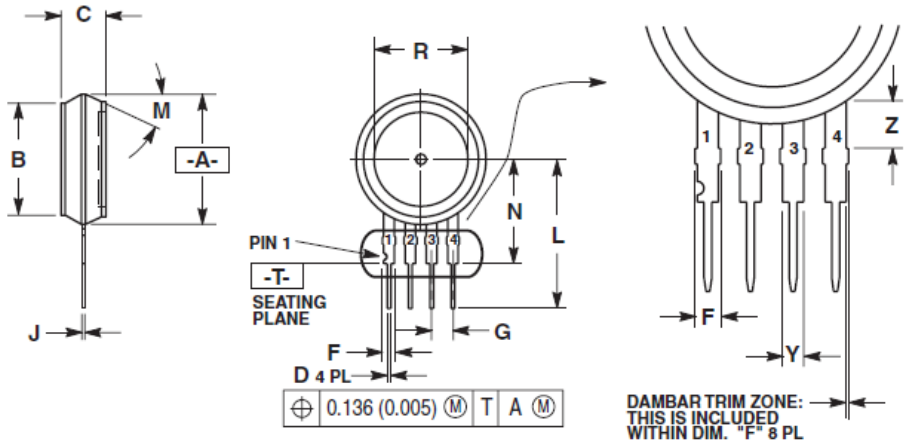
7 PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

ST designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing silicone gel which isolates the die from the environment. The ST MPX pressure sensor is designed to operate with positive differential pressure applied, P1 > P2. The Pressure (P1) side may be identified by using the following table.

Part Number	Case Type	Pressure (P1) Side Identifier
MPX2200D/A	344	Stainless Steel Cap
MPX2200DP	344C	Side with Part Marking
MPX2200GP/AP	344B	Side with Port Attached

8 PACKAGE DIMENSIONS

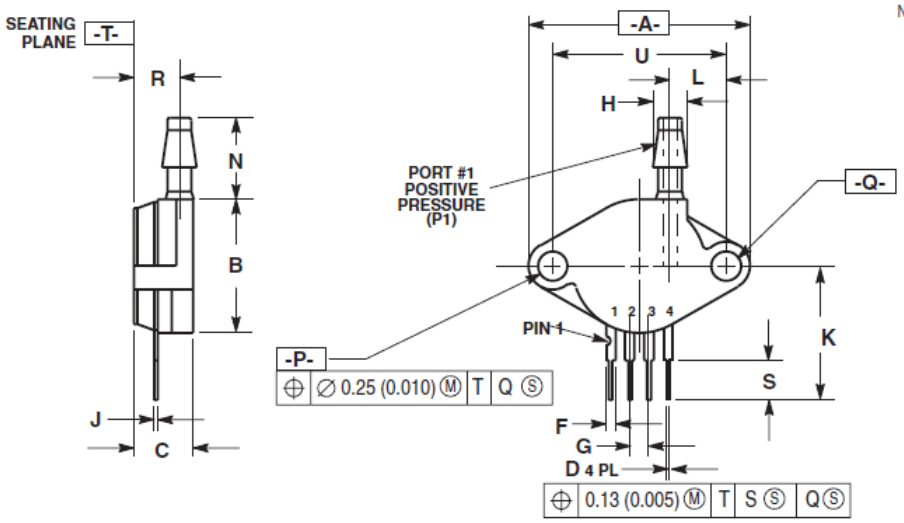
Figure 5. **CASE 344-15 ISSUE AA UNIBODY PACKAGE**



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.595	0.630	15.11	16.00
B	0.514	0.534	13.06	13.56
C	0.200	0.220	5.08	5.59
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.40
L	0.695	0.725	17.65	18.42
M	30° NOM		30° NOM	
N	0.475	0.495	12.07	12.57
R	0.430	0.450	10.92	11.43
Y	0.048	0.052	1.22	1.32
Z	0.106	0.118	2.68	3.00

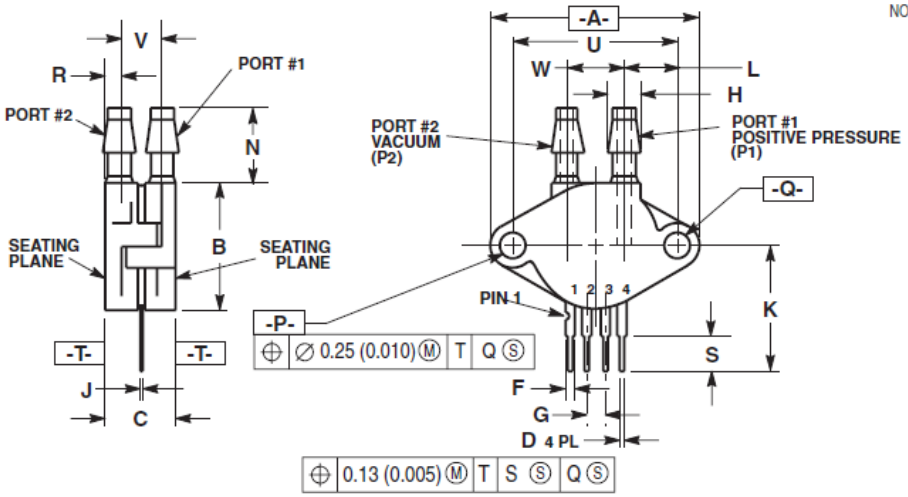
Figure 6. **CASE 344B-01 ISSUE B UNIBODY PACKAGE**



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.305	0.325	7.75	8.26
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.230	0.250	5.84	6.35
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	

Figure 7. **CASE 344C-01 ISSUE B UNIBODY PACKAGE**



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.016	0.020	0.41	0.51
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
H	0.182	0.194	4.62	4.93
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.248	0.278	6.30	7.06
W	0.310	0.330	7.87	8.38

Revision history

Table 2. **Document revision history**

Date	Version	Changes
11-Jun-2026	1	Initial release from ST, rebranded NXP document

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